

ABSTRACT

The present invention provides a metal surface protective film-forming agent that contains an α -amino acid (e.g., leucine, phenylalanine and valine) and a metal polishing solution using the same. The present invention also provides a method of polishing a surface 5 of a base material for the manufacture of a substrate for semiconductor circuits, a method of forming a metal surface protective film, the use of the particular amino acid to the metal surface protective film forming agent, a substrate for semiconductor circuit that uses the same, a semiconductor circuit including these and a method of manufacturing the same.